Fukuda exhibited its products at the nanomicro biz exhibition

Fukuda Co., Ltd. have exhibited our products at the nanomicro biz exhibition, which had commenced on April 22, 2015 (Monday).

We would like to thank you for visiting our booth.

Overview

Exhibition Dates

April 22 (Wed.) - April 24 (Fri.)
10:00-17:00

Location

Pacifico Yokohama Exhibition Hall B, Booth Number D-4

Products on Display

We will exhibit and demonstrate our air leak testers for hermetically sealed electronic components (MEMS devices, crystal oscillators, semiconductor packages, etc.).

Seminar

Title: "MEMS package leak testing: its latest technology and trends"
Location: Exhibition Hall B, Presentation Room
Date: April 24, (Fri.)　13:30-13:50
Contents (subject to change)

- The current state of play in the field of leak testing; Fukuda's initiatives in the industry
- Introduction of our MEMS leak tester (4×10^{-15}Pa･m^3/s(He))

Co-located with

OPIE'15 (OPTICS & PHOTONICS International Exhibition - a combination of exhibitions in 6 different categories)

Exhibition Website

http://www.micromachine.jp/en/

nanomicro biz
ROBOTECH

FUKUDA CO., LTD.

2015.4.22～2015.4.24

Products on Display

Air Leak Tester
FL-611 series

- Differential pressure type air leak tester that utilizes the changes in air pressure
- It is highly versatile and is suitable for mass production lines
- Measurements can be carried out without a reference unit

Applicable test parts
Engine components, transmission components, fuel system components, brake components, batteries, heat exchangers, air conditioners, lithium ion secondary batteries, FC cells, FC modules, FC tanks, etc.

Hydrogen leak detectors
HD-111 series

- This series comes with a probe, and is suited for specifying the location of the leak
- Uses a safe trace gas containing 5% hydrogen and 95% nitrogen

Applicable test parts
Inverter, converters, harnesses, battery cases, secondary batteries, FC cells, FC modules, FC tanks, Smartphone (detecting leak location), secondary batteries, etc.

Hermetically Sealed Electronic Components Leak Test System
MSX-0100 series

- Suited for small-volume production of sealed products or to analyze the characteristics of a product during R&D
- This equipment carries out bombing, gross/fine leak tester under a single, integrated unit
- Helium bombing time and dwell time can also be managed

Applicable test parts
MEMS device, relay, etc.

Hermetically Sealed Electronic Components Leak Test System
MSX-6200 series

NEW

- Fully-automated Leak Test System
- Compatible with 2016 and 2520
- Minimum detectable leak rate of 1×10^{-9}Pa･m^3/s (He)
- Tact time of　0.8 sec./pc

Applicable test parts
SMDs, SAW filters, MEMS devices, etc.

Ultra Fine Leak Test System
MUH-0100 series

NEW

- This device uses helium gas for measuring ultra-fine leaks
- Leak rate judgment level　4×10^{-15} Pa･m^3/s (He)
- Maximum size of the tested component
  Φ44 × L31mm(rectangular: 30 × 30)

Applicable test parts
MEMS devices (pressure sensors, accelerometer, angular velocity sensor, infrared image sensor) etc.

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